

PART INFORMATION		
Mfg Item Number		KSCU7119VF1200
Mfg Item Name		MAPBGA 400 17*17*0.8P0.8
SUPPLIER		
Company Name		Freescale Semiconductor Inc
Company Unique ID		14-141-7928
Response Date		2018-05-07
Response Document ID		5284K10971D052A1.8
Contact Name		Freescale Semiconductor Inc
Contact Title		Product Technical Support
Contact Phone		1-800-521-6274
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Authorized Representative		Daniel Binyon
Representative Title		EPP Customer Response
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Representative Email		eppanlst@freescale.com
URL for Additional Information		www.freescale.com
DECLARATION		
EU RoHS		No
Pb Free		No
HalogenFree		Yes
Plating Indicator		e0
EU RoHS Exemption(s)		
MANUFACTURING		
Mfg Item Number		KSCU7119VF1200
Mfg Item Name		MAPBGA 400 17*17*0.8P0.8
Version		ALL
Weight		0.861400
UoM		g
Unit Volume		EACH
J-STD-020 MSL Rating		3
Peak Processing Temperature		260 C
Max Time at Peak Temperature		40 seconds
Number of Processing Cycles		3

RoHS	
RoHS Directive	2011/65/EU
RoHS Definition	RoHS Definition: Quantity limit of 0.1% by mass (1000 PPM) of homogeneous material for: Lead (Pb), Mercury, Hexavalent Chromium, Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE) and quantity limit of 0.01% by mass (100 PPM) of homogeneous material of Cadmium
RoHS Legal Definition	Please indicate whether any homogeneous material (as defined by the RoHS Directive, EU 2011/65/EU and implemented by the laws of the European Union member states) of the part(s) identified on this form contains lead, mercury, cadmium, hexavalent chromium, polybrominated biphenyls and/or polybrominated diphenyl ethers (each a RoHS restricted substance) in excess of the applicable quantity limit identified below. If a homogeneous material within the part(s) contains a RoHS restricted substance in excess of an applicable quantity limit, please indicate below which, if any, RoHS exemption you believe may apply. If the part is an assembly with lower level components, the declaration shall encompass all such components. Supplier certifies that it gathered the information it provides in this form using appropriate methods to ensure its accuracy and that such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products with European Union member state laws that implement the RoHS Directive. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Suppliers liability and the Companys remedies for issues that arise regarding information the Supplier provides in this form. In the absence of such written agreement, the warranty rights and/or remedies of Suppliers Standard Terms and Conditions of Sale applicable to such part(s) shall apply.
RoHS Declaration	3 - Item(s) does not contain RoHS restricted substances per the definition above except for lead in solders and selected exemptions, if any
Supplier Acceptance	Accepted
Signature	Daniel Binyon
Exemption List Version	2012/51/EU
List of Freescale Accepted Exemptions	6(a) : Lead as an alloying element in steel for machining purposes and in galvanized steel containing up to 0.35% lead by weight 6(b) : Lead as an alloying element in aluminium containing up to 0.4% lead by weight 6(c) : Copper alloy containing up to 4% lead by weight 7(a) : Lead in high melting temperature type solders (i.e. lead-based alloys containing 85% by weight or more lead) 7(b) : Lead in solders for servers, storage and storage array systems, network infrastructure equipment for switching, signaling, transmission, and network management for telecommunications 7(c)-I : Electrical and electronic components containing lead in a glass or ceramic other than dielectric ceramic in capacitors, e.g. piezoelectronic devices, or in a glass or ceramic matrix compound 7(c)-II : Lead in dielectric ceramic in capacitors for a rated voltage of 125 V AC or 250 V DC or higher 7(c)-III : Lead in dielectric ceramic in capacitors for a rated voltage of less than 125 V AC or 250 V DC 7(c)-IV : Lead in PZT based dielectric ceramic materials for capacitors being part of integrated circuits or discrete semiconductors 15 : Lead in solders to complete a viable electrical connection between semiconductor die and carrier within integrated circuit flip chip packages

MATERIAL COMPOSITION

Homogeneous Material	Weight	SubstanceClass	Substance	CAS	Exemption	SubstanceWeight	UoM	SubPart PPM	SubPart%		ARTICLEPPM	ARTICLE%
Solder Balls - Low Lead	0.1261						g					
Solder Balls - Low Lead		Lead/Lead Compounds	Lead	7439-92-1		0.045396	g	360000	36		52700	5.27
Solder Balls - Low Lead		Metals	Silver, metal	7440-22-4		0.002522	g	20000	2		2927	0.2927
Solder Balls - Low Lead		Metals	Tin, metal	7440-31-5		0.078182	g	620000	62		90761	9.0761
Non-Conductive Epoxy/Adhesive	0.0043						g					
Non-Conductive Epoxy/Adhesive		Plastics/polymers	Proprietary Material-Other Epoxy resins	-		0.0003225	g	75000	7.5		374	0.0374
Non-Conductive Epoxy/Adhesive		Plastics/polymers	Crosslinked acrylate polymer	25767-43-5		0.00086	g	200000	20		998	0.0998
Non-Conductive Epoxy/Adhesive		Plastics/polymers	Other polymers	-		0.0003225	g	75000	7.5		374	0.0374
Non-Conductive Epoxy/Adhesive		Plastics/polymers	Proprietary Material-Other polymers	-		0.00086	g	200000	20		998	0.0998
Non-Conductive Epoxy/Adhesive		Glass	Silica, vitreous	60676-86-0		0.001935	g	450000	45		2246	0.2246
Silicon Semiconductor Die	0.0335						g					
Silicon Semiconductor Die		Solvents, additives, and other materials	Other miscellaneous substances (less than 5%).	-		0.00067	g	20000	2		777	0.0777
Silicon Semiconductor Die		Glass	Silicon, doped	-		0.03283	g	980000	98		38112	3.8112
Organic Substrate, Halogen-free	0.294						g					
Organic Substrate, Halogen-free		Metals	Barium sulfate	7727-43-7		0.01043259	g	35485	3.5485		12111	1.2111
Organic Substrate, Halogen-free		Metals	Copper, metal	7440-50-8		0.13243288	g	450452	45.0452		153741	15.3741
Organic Substrate, Halogen-free		Plastics/polymers	Epikote 862	28064-14-4		0.01849613	g	62912	6.2912		21472	2.1472
Organic Substrate, Halogen-free		Plastics/polymers	Other Epoxy resins	-		0.01616324	g	54977	5.4977		18763	1.8763
Organic Substrate, Halogen-free		Metals	Gold, metal	7440-57-5		0.00082085	g	2792	0.2792		952	0.0952
Organic Substrate, Halogen-free		Nickel (external applications only)	Nickel	7440-02-0		0.00641126	g	21807	2.1807		7442	0.7442
Organic Substrate, Halogen-free		Plastics/polymers	Phenol, polymer with formaldehyde	9003-35-4		0.01010037	g	34355	3.4355		11725	1.1725
Organic Substrate, Halogen-free		Glass	Fibrous-glass-wool	65997-17-3		0.06186407	g	210422	21.0422		71818	7.1818
Organic Substrate, Halogen-free		Glass	Silicon dioxide	7631-86-9		0.00530258	g	18036	1.8036		6155	0.6155
Organic Substrate, Halogen-free		Solvents, additives, and other materials	Other Aromatic carbonyl compounds	-		0.00167521	g	5698	0.5698		1944	0.1944
Organic Substrate, Halogen-free		Metals	Aluminum Hydroxide	21645-61-2		0.03030082	g	103064	10.3064		35176	3.5176
Die Encapsulant, Halogen-free	0.3984						g					
Die Encapsulant, Halogen-free		Solvents, additives, and other materials	Acrylonitrile/Butadiene copolymer, carboxyl terminated (2674)	68891-46-3		0.0001992	g	500	0.05		231	0.0231
Die Encapsulant, Halogen-free		Metals	Proprietary Material-Other aluminum compounds	-		0.003984	g	10000	1		4625	0.4625
Die Encapsulant, Halogen-free		Plastics/polymers	Other Epoxy resins	-		0.00996	g	25000	2.5		11562	1.1562
Die Encapsulant, Halogen-free		Plastics/polymers	Proprietary Material-Other Epoxy resins	-		0.00996	g	25000	2.5		11562	1.1562
Die Encapsulant, Halogen-free		Solvents, additives, and other materials	Carbon Black	1333-86-4		0.001992	g	5000	0.5		2312	0.2312
Die Encapsulant, Halogen-free		Plastics/polymers	Proprietary Material-Other phenolic resins	-		0.015936	g	40000	4		18500	1.85
Die Encapsulant, Halogen-free		Glass	Silicon dioxide	7631-86-9		0.07968	g	200000	20		92500	9.25
Die Encapsulant, Halogen-free		Glass	Silica, vitreous	60676-86-0		0.2766888	g	694500	69.45		321223	32.1223
Bonding Wire, PdCu	0.0051						g					
Bonding Wire, PdCu		Metals	Copper, metal	7440-50-8		0.00497938	g	976350	97.635		5780	0.578
Bonding Wire, PdCu		Metals	Gold, metal	7440-57-5		0.00000665	g	1696	0.1696		10	0.001
Bonding Wire, PdCu		Metals	Palladium, metal	7440-05-3		0.00011197	g	21954	2.1954		129	0.0129

LINKS	
MCD LINK	
NXP website	http://www.nxp.com
GENERAL ENVIRONMENTAL COMPLIANCE LINKS	
RoHS signed letter	http://www.nxp.com/files/corporate/doc/support_info/NXP-ROHS-DECLARATION.pdf
China RoHS	http://www.nxp.com/about/corporate-responsibility/environmental-compliance-organization/china-rohs:ENV_CHINA_ROHS_STRATEGY
REACH signed letter	http://www.nxp.com/files/corporate/doc/support_info/NXP-REACH-STATEMENT.pdf
ELV signed letter	http://www.nxp.com/files/corporate/doc/support_info/NXP-ELV-STATEMENT.pdf
Conflict Minerals statement	http://www.nxp.com/files/corporate/doc/support_info/NXP-STATEMENT-CONFLICT-MINERALS.pdf
NXP ENVIRONMENTAL INFORMATION	
Environmental Compliance website	http://www.nxp.com/about/corporate-responsibility/environmental-compliance-organization:ABUENVPRFPRDX
FAQ	http://www.nxp.com/about/corporate-responsibility/environmental-compliance-organization/eco-product-faqs:ENVIRON_FAQ
Technical Service Request	http://www.nxp.com/support/sales-and-support:SUPPORTHOME
LINKS TO BLANK IPC1752 FORMS	
Blank IPC1752 v1.1 Form	http://www.NXP.com/files/abstract/corporate/ehs_epp/IPC-1752-2_v1.1_MCD_Template.pdf

IPC1752 XML LINKS

http://www.freescale.com/mcds/KSCU7119VF1200_IPC1752_v11.xml

http://www.freescale.com/mcds/KSCU7119VF1200_IPC1752A.xml